SMOOTH N SLEEK SDN BHD

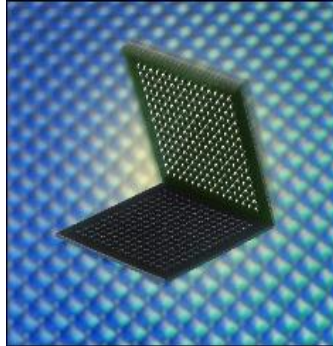**(Co. Reg. No: 321141-K)**   ***ESTD. SINCE 1994***
UNIT 1-05-12, KRYSTAL POINT CORPORATE PARK, KRYSTAL POINT II,
LEBUH BUKIT KECIL 6, 11900 BAYAN LEPAS, PENANG, MALAYSIA.
TEL : (6)04-644 8029, 644 9029   FAX : (6)04-644 0107   E-mail : sales@snspcb.com
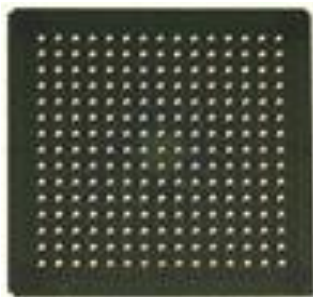WEBSITE : www.snspcb.com

EZReball™

Are you tired of the existing reballing methods being in the hands of process experts due to the complexities and the dexterity required? Are you looking for a faster reballing method? The new EZReball™ process is an answer to your reballing problems. This unique method simplifies the reballing process allowing for better yields and faster reballing times.

The simple nature of the EZReball™ reballing process allows even the beginning repair technician to reliably and quickly replace balls on a BGA package. Alignment is simple with the edges of the preform being "squared up" with the sides of the package thereby eliminating the need to buy custom fixtures or frames. The adhesive is engineered such that the balls are firmly held in place until after reflow thereby reducing the problem of missing solder balls found in other techniques. After the device has been reflowed, the preform is simply peeled off, eliminating the time required in cleaning off residual paper used in other methods.
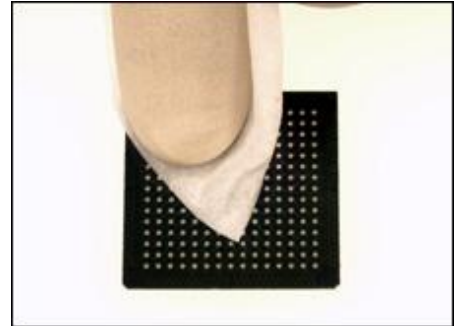
The EZReball™ preforms are packaged and delivered to you the way you want. Preforms are custom made to your exact alloy and device array requirements without expensive tooling. They are also packaged such that developers and those building PCB prototypes can use them in quantities that are more reasonable.
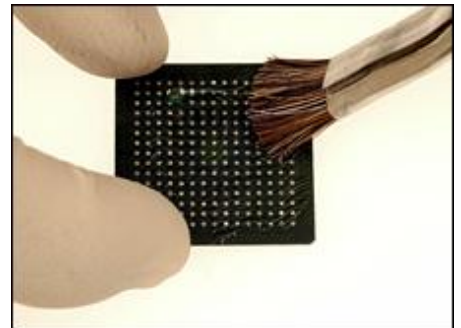
These reballing preforms are a simple, elegant and easy-to-use reballing system. EZReball™ preforms are manufactured to your exacting specifications from a specialty high temperature-rated film which aligns the balls. The balls are aligned through these apertures and held in place using an engineered adhesive system. The preform is cut using a laser to your exacting device requirements. Solder balls are captured and retained by the preform and are aligned to the prepped device and reflowed. After reflow the preform is simply peeled away. EZReball™ reballing preforms are packaged in groups of (15) in a small antistatic bag. Each packet also consists of (1) repair re-balling pre-form which gives the user a QC tool to inspect that the reballed device and to simplify the rework if a single ball needed to be reworked.
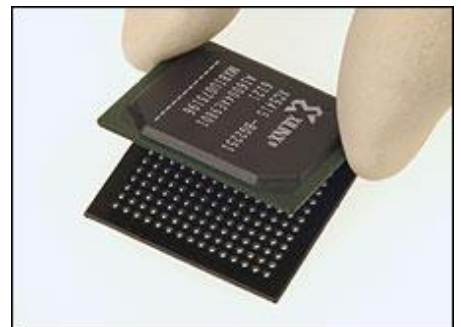
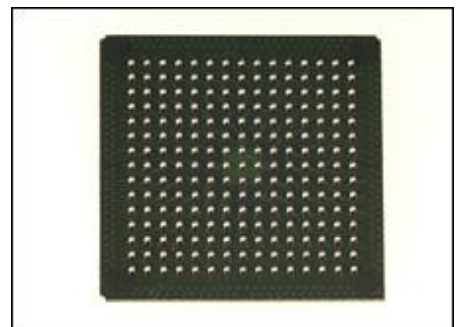**EZReball™ SPEEDS DEVICE REBALLING!**

1. Dress Site and Clean

2. Apply Paste Flux

3. Align and Place BGA on to Preform

4. Post Reflow and Preform Removal